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H8S/2426, H8S/2426R, H8S/2424 Group

User's Manual: Hardware

Renesas 16-Bit Single-Chip Microcomputer H8S Family / H8S/2400 Series

H8S/2426	R4F2426
	R4S2426
H8S/2426R	R4F2426R
	R4S2426R
H8S/2424	R4F2424
	R4S2424

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General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions may occur due to the false recognition of the pin state as an input signal. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

- The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.

How to Use This Manual

1. Purpose and Target Readers

This manual is designed to provide the user with an understanding of the hardware functions and electrical characteristics of the MCU. It is intended for users designing application systems incorporating the MCU. A basic knowledge of electric circuits, logical circuits, and MCUs is necessary in order to use this manual.

The manual comprises an overview of the product; descriptions of the CPU, system control functions, peripheral functions, and electrical characteristics; and usage notes.

Particular attention should be paid to the precautionary notes when using the manual. These notes occur within the body of the text, at the end of each section, and in the Usage Notes section.

The revision history summarizes the locations of revisions and additions. It does not list all revisions. Refer to the text of the manual for details.

The following documents apply to the H8S/2426, H8S/2426R, H8S/2424 Group. Make sure to refer to the latest versions of these documents. The newest versions of the documents listed may be obtained from the Renesas Electronics Web site.

Document Type	Contents	Document Title	Document No.
Data Sheet	Hardware overview and electrical characteristics	—	—
User's manual for Hardware	Hardware specifications (pin assignments, memory maps, peripheral function specifications, electrical characteristics, timing charts) and operation description	H8S/2426, H8S/2426R, H8S/2424 Group User's manual for Hardware	This User's manual
User's manual for Software	Note: Refer to the application notes for details on using peripheral functions.	H8S/2600 Series H8S/2000 Series Software Manual	REJ09B0139
Application Note	Description of CPU instruction set	Available from Renesas Electronics Web site.	
Renesas Technical Update	Information on using peripheral functions and application examples		

2. Description of Numbers and Symbols

Aspects of the notations for register names, bit names, numbers, and symbolic names in this manual are explained below.

(1) Overall notation

In descriptions involving the names of bits and bit fields within this manual, the modules and registers to which the bits belong may be clarified by giving the names in the forms "module name". "register name". "bit name" or "register name". "bit name".

(2) Register notation

The style "register name"_"instance number" is used in cases where there is more than one instance of the same function or similar functions.

[Example] CMCSR_0: Indicates the CMCSR register for the compare-match timer of channel 0.

(3) Number notation

Binary numbers are given as B'nnnn (B' may be omitted if the number is obviously binary), hexadecimal numbers are given as H'nnnn or 0xnnnn, and decimal numbers are given as nnnn.

[Examples] Binary: B'11 or 11

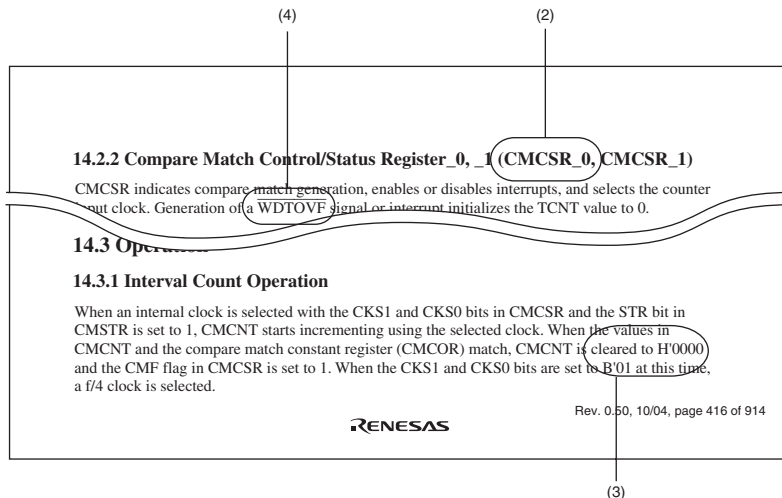
Hexadecimal: H'EFA0 or 0xEFA0

Decimal: 1234

(4) Notation for active-low

An overbar on the name indicates that a signal or pin is active-low.

[Example] $\overline{\text{WDTOVF}}$



Note: The bit names and sentences in the above figure are examples and have nothing to do with the contents of this manual.

3. Description of Registers

Each register description includes a bit chart, illustrating the arrangement of bits, and a table of bits, describing the meanings of the bit settings. The standard format and notation for bit charts and tables are described below.

[Table of Bits]

(1) Bit	(2) Bit Name	(3) Initial Value	(4) R/W	(5) Description
15	—	0	R	Reserved
14	—	0	R	These bits are always read as 0.
13 to 11	ASID2 to ASID0	All 0	R/W	Address Identifier These bits enable or disable the pin function.
10	—	0	R	Reserved This bit is always read as 0.
9	—	1	R	Reserved This bit is always read as 1.
—	—	0	—	—

Note: The bit names and sentences in the above figure are examples, and have nothing to do with the contents of this manual.

- (1) Bit
Indicates the bit number or numbers.
In the case of a 32-bit register, the bits are arranged in order from 31 to 0. In the case of a 16-bit register, the bits are arranged in order from 15 to 0.
- (2) Bit name
Indicates the name of the bit or bit field.
When the number of bits has to be clearly indicated in the field, appropriate notation is included (e.g., ASID[3:0]).
A reserved bit is indicated by "—".
Certain kinds of bits, such as those of timer counters, are not assigned bit names. In such cases, the entry under Bit Name is blank.
- (3) Initial value
Indicates the value of each bit immediately after a power-on reset, i.e., the initial value.
0: The initial value is 0
1: The initial value is 1
—: The initial value is undefined
- (4) R/W
For each bit and bit field, this entry indicates whether the bit or field is readable or writable, or both writing to and reading from the bit or field are impossible.
The notation is as follows:
R/W: The bit or field is readable and writable.
R/(W): The bit or field is readable and writable.
However, writing is only performed to flag clearing.
R: The bit or field is readable.
"R" is indicated for all reserved bits. When writing to the register, write the value under Initial Value in the bit chart to reserved bits or fields.
W: The bit or field is writable.
- (5) Description
Describes the function of the bit or field and specifies the values for writing.

4. Description of Abbreviations

The abbreviations used in this manual are listed below.

- Abbreviations specific to this product

Abbreviation	Description
BSC	Bus controller
CPG	Clock pulse generator
INT	Interrupt controller
SCI	Serial communication interface
TMR	8-bit timer
TPU	16-bit timer pulse unit
WDT	Watchdog timer

- Abbreviations other than those listed above

Abbreviation	Description
ACIA	Asynchronous communications interface adapter
bps	Bits per second
CRC	Cyclic redundancy check
DMA	Direct memory access
DMAC	Direct memory access controller
GSM	Global System for Mobile Communications
Hi-Z	High impedance
IEBus	—
I/O	Input/output
IrDA	Infrared Data Association
LSB	Least significant bit
MSB	Most significant bit
NC	No connection
PLL	Phase-locked loop
PWM	Pulse width modulation
SFR	Special function register
SIM	Subscriber Identity Module
UART	Universal asynchronous receiver/transmitter
VCO	Voltage-controlled oscillator

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Contents

Section 1	Overview.....	1
1.1	Features.....	1
1.1.1	Applications.....	1
1.1.2	Overview of Specifications.....	2
1.2	List of Products.....	9
1.3	Block Diagrams	14
1.4	Pin Description	16
1.4.1	Pin Assignments	16
1.4.2	Pin Assignments in Each Operating Mode	19
1.4.3	Pin Functions	33
Section 2	CPU.....	45
2.1	Features.....	45
2.1.1	Differences between H8S/2600 CPU and H8S/2000 CPU	46
2.1.2	Differences from H8/300 CPU	47
2.1.3	Differences from H8/300H CPU	48
2.2	CPU Operating Modes.....	49
2.2.1	Normal Mode.....	49
2.2.2	Advanced Mode.....	51
2.3	Address Space.....	53
2.4	Registers	54
2.4.1	General Registers.....	55
2.4.2	Program Counter (PC)	56
2.4.3	Extended Register (EXR)	56
2.4.4	Condition-Code Register (CCR).....	57
2.4.5	Multiply-Accumulate Register (MAC).....	58
2.4.6	Initial Values of CPU Internal Registers.....	58
2.5	Data Formats.....	59
2.5.1	General Register Data Formats.....	59
2.5.2	Memory Data Formats.....	61
2.6	Instruction Set.....	62
2.6.1	Table of Instructions Classified by Function	63
2.6.2	Basic Instruction Formats	72
2.7	Addressing Modes and Effective Address Calculation.....	74
2.7.1	Register Direct—Rn	74
2.7.2	Register Indirect—@ERn.....	74

2.7.3	Register Indirect with Displacement—@ (d:16, ERn) or @ (d:32, ERn).....	75
2.7.4	Register Indirect with Post-Increment or Pre-Decrement—@ERn+ or @-ERn.....	75
2.7.5	Absolute Address—@aa:8/@aa:16/@aa:24/@aa:32.....	75
2.7.6	Immediate—#xx:8/#xx:16/#xx:32.....	76
2.7.7	Program-Counter Relative—@ (d:8, PC) or @ (d:16, PC)	76
2.7.8	Memory Indirect—@ @aa:8	77
2.7.9	Effective Address Calculation	78
2.8	Processing States.....	80
2.9	Usage Note.....	82
2.9.1	Usage Notes on Bit-wise Operation Instructions	82
Section 3 MCU Operating Modes		83
3.1	Operating Mode Selection	83
3.2	Register Descriptions	84
3.2.1	Mode Control Register (MDCR)	84
3.2.2	System Control Register (SYSCR).....	84
3.3	Operating Mode Descriptions	86
3.3.1	Mode 1.....	86
3.3.2	Mode 2.....	86
3.3.3	Mode 3.....	86
3.3.4	Mode 4.....	87
3.3.5	Mode 7.....	87
3.3.6	Pin Functions	88
3.4	Memory Map in Each Operating Mode	88
Section 4 Exception Handling		95
4.1	Exception Handling Types and Priority	95
4.2	Exception Sources and Exception Vector Table	96
4.3	Reset	98
4.3.1	Reset Exception Handling	98
4.3.2	Interrupts after Reset.....	100
4.3.3	On-Chip Peripheral Functions after Reset Release	100
4.4	Trace Exception Handling	101
4.5	Interrupt Exception Handling	102
4.6	Trap Instruction Exception Handling.....	103
4.7	Illegal Instruction Exception Handling	104
4.8	Stack Status after Exception Handling.....	105
4.9	Usage Note.....	106

Section 5	Interrupt Controller	107
5.1	Features.....	107
5.2	Input/Output Pins	109
5.3	Register Descriptions	110
5.3.1	Interrupt Control Register (INTCR)	111
5.3.2	Interrupt Priority Registers A to N (IPRA to IPRN).....	112
5.3.3	IRQ Enable Register (IER).....	114
5.3.4	IRQ Sense Control Registers H and L (ISCRH, ISCRL).....	116
5.3.5	IRQ Status Register (ISR).....	122
5.3.6	IRQ Pin Select Register (ITSR).....	123
5.3.7	Software Standby Release IRQ Enable Register (SSIER).....	126
5.4	Interrupt Sources.....	127
5.4.1	External Interrupts	127
5.4.2	Internal Interrupts	128
5.5	Interrupt Exception Handling Vector Table.....	129
5.6	Interrupt Control Modes and Interrupt Operation	136
5.6.1	Interrupt Control Mode 0.....	137
5.6.2	Interrupt Control Mode 2.....	139
5.6.3	Interrupt Exception Handling Sequence	141
5.6.4	Interrupt Response Times	143
5.6.5	DTC and DMAC Activation by Interrupt	144
5.7	Usage Notes	145
5.7.1	Conflict between Interrupt Generation and Disabling	145
5.7.2	Instructions that Disable Interrupts	146
5.7.3	Times when Interrupts are Disabled	146
5.7.4	Interrupts during Execution of EEPMOV Instruction	146
5.7.5	Change of IRQ Pin Select Register (ITSR) Setting	146
5.7.6	IRQ Status Register (ISR).....	147
Section 6	Bus Controller (BSC).....	149
6.1	Features.....	149
6.2	Input/Output Pins	152
6.3	Register Descriptions	155
6.3.1	Bus Width Control Register (ABWCR).....	156
6.3.2	Access State Control Register (ASTCR)	156
6.3.3	Wait Control Registers AH, AL, BH, and BL (WTCRAH, WTCRAL, WTCRBH, and WTCRBL)	157
6.3.4	Read Strobe Timing Control Register (RDNCR)	163
6.3.5	$\overline{\text{CS}}$ Assertion Period Control Registers H, L (CSACRH, CSACRL).....	165

6.3.6	Area 0 Burst ROM Interface Control Register (BROMCRH)	
	Area 1 Burst ROM Interface Control Register (BROMCRL)	167
6.3.7	Bus Control Register (BCR)	168
6.3.8	Address/Data Multiplexed I/O Control Register (MPXCR)	170
6.3.9	DRAM Control Register (DRAMCR)	171
6.3.10	DRAM Access Control Register (DRACCR).....	179
6.3.11	Refresh Control Register (REFCR)	182
6.3.12	Refresh Timer Counter (RTCNT).....	185
6.3.13	Refresh Time Constant Register (RTCOR)	185
6.4	Bus Control.....	186
6.4.1	Area Division.....	186
6.4.2	Bus Specifications	187
6.4.3	Memory Interfaces.....	189
6.4.4	Chip Select Signals	191
6.5	Basic Bus Interface	193
6.5.1	Data Size and Data Alignment.....	193
6.5.2	Valid Strobes	195
6.5.3	Basic Timing.....	196
6.5.4	Wait Control	204
6.5.5	Read Strobe ($\overline{RD}$) Timing.....	205
6.5.6	Extension of Chip Select ($\overline{CS}$) Assertion Period.....	207
6.6	Address/Data Multiplexed I/O Interface.....	208
6.6.1	Setting Address/Data Multiplexed I/O Space	208
6.6.2	Address/Data Multiplexing	208
6.6.3	Data Bus	209
6.6.4	Address Hold Signal.....	209
6.6.5	Basic Timing.....	209
6.6.6	Wait Control	218
6.6.7	Read Strobe ($\overline{RD}$) Timing.....	219
6.6.8	Extension of Chip Select ($\overline{CS}$) Assertion Period in Data Cycle.....	220
6.7	DRAM Interface	222
6.7.1	Setting DRAM Space.....	222
6.7.2	Address Multiplexing	222
6.7.3	Data Bus	223
6.7.4	Pins Used for DRAM Interface.....	224
6.7.5	Basic Timing.....	225
6.7.6	Column Address Output Cycle Control	227
6.7.7	Row Address Output State Control.....	228
6.7.8	Precharge State Control	230
6.7.9	Wait Control	231

6.7.10	Byte Access Control	234
6.7.11	Burst Operation.....	236
6.7.12	Refresh Control.....	241
6.7.13	DMAC and EXDMAC Single Address Transfer Mode and DRAM Interface.....	247
6.8	Synchronous DRAM Interface.....	250
6.8.1	Setting Continuous Synchronous DRAM Space.....	250
6.8.2	Address Multiplexing	251
6.8.3	Data Bus	252
6.8.4	Pins Used for Synchronous DRAM Interface.....	252
6.8.5	Synchronous DRAM Clock.....	254
6.8.6	Basic Timing.....	254
6.8.7	CAS Latency Control.....	256
6.8.8	Row Address Output State Control.....	258
6.8.9	Precharge State Count.....	259
6.8.10	Bus Cycle Control in Write Cycle	261
6.8.11	Byte Access Control	262
6.8.12	Burst Operation.....	265
6.8.13	Refresh Control.....	269
6.8.14	Mode Register Setting of Synchronous DRAM.....	275
6.8.15	DMAC and EXDMAC Single Address Transfer Mode and Synchronous DRAM Interface	276
6.9	Burst ROM Interface.....	281
6.9.1	Basic Timing.....	281
6.9.2	Wait Control	283
6.9.3	Write Access.....	283
6.10	Idle Cycle.....	284
6.10.1	Operation	284
6.10.2	Pin States in Idle Cycle.....	303
6.11	Write Data Buffer Function	304
6.12	Bus Release.....	305
6.12.1	Operation	305
6.12.2	Pin States in External Bus Released State	306
6.12.3	Transition Timing	307
6.13	Bus Arbitration	309
6.13.1	Operation	309
6.13.2	Bus Transfer Timing.....	310
6.14	Bus Controller Operation in Reset.....	311
6.15	Usage Notes	312
6.15.1	External Bus Release Function and All-Module-Clocks-Stopped Mode.....	312
6.15.2	External Bus Release Function and Software Standby	312

6.15.3	External Bus Release Function and CBR Refreshing/Auto Refreshing.....	312
6.15.4	$\overline{\text{BREQO}}$ Output Timing	313
6.15.5	Notes on Usage of the Synchronous DRAM	313
Section 7 DMA Controller (DMAC).....		315
7.1	Features.....	315
7.2	Input/Output Pins	317
7.3	Register Descriptions	318
7.3.1	Memory Address Registers (MARA and MARB).....	320
7.3.2	I/O Address Registers (IOARA and IOARB).....	321
7.3.3	Execute Transfer Count Registers (ETCRA and ETCRB)	321
7.3.4	DMA Control Registers (DMACRA and DMACRB)	323
7.3.5	DMA Band Control Registers H and L (DMABCRH and DMABCRL).....	331
7.3.6	DMA Write Enable Register (DMAWER).....	342
7.3.7	DMA Terminal Control Register (DMATCR)	344
7.4	Activation Sources	345
7.4.1	Activation by Internal Interrupt Request	346
7.4.2	Activation by Auto-Request	347
7.5	Operation	347
7.5.1	Transfer Modes	347
7.5.2	Sequential Mode	350
7.5.3	Idle Mode.....	353
7.5.4	Repeat Mode.....	356
7.5.5	Single Address Mode.....	360
7.5.6	Normal Mode.....	363
7.5.7	Block Transfer Mode	367
7.5.8	Basic Bus Cycles	373
7.5.9	DMA Transfer (Dual Address Mode) Bus Cycles.....	374
7.5.10	DMA Transfer (Single Address Mode) Bus Cycles	384
7.5.11	Write Data Buffer Function	392
7.5.12	Multi-Channel Operation.....	394
7.5.13	Relation between DMAC and External Bus Requests, Refresh Cycles, and EXDMAC	396
7.5.14	DMAC and NMI Interrupts	397
7.5.15	Forced Termination of DMAC Operation	398
7.5.16	Clearing Full Address Mode.....	399
7.6	Interrupt Sources.....	400
7.7	Usage Notes	401

Section 8	EXDMA Controller (EXDMAC)	407
8.1	Features	407
8.2	Input/Output Pins	409
8.3	Register Descriptions	410
8.3.1	EXDMA Source Address Register (EDSAR)	410
8.3.2	EXDMA Destination Address Register (EDDAR)	411
8.3.3	EXDMA Transfer Count Register (EDTCR)	411
8.3.4	EXDMA Mode Control Register (EDMDR)	413
8.3.5	EXDMA Address Control Register (EDACR)	418
8.4	Operation	422
8.4.1	Transfer Modes	422
8.4.2	Address Modes	423
8.4.3	DMA Transfer Requests	427
8.4.4	Bus Modes	428
8.4.5	Transfer Modes	430
8.4.6	Repeat Area Function	432
8.4.7	Registers during DMA Transfer Operation	435
8.4.8	Channel Priority Order	439
8.4.9	EXDMAC Bus Cycles (Dual Address Mode)	442
8.4.10	EXDMAC Bus Cycles (Single Address Mode)	449
8.4.11	Examples of Operation Timing in Each Mode	454
8.4.12	Ending DMA Transfer	468
8.4.13	Relationship between EXDMAC and Other Bus Masters	469
8.5	Interrupt Sources	470
8.6	Usage Notes	472
Section 9	Data Transfer Controller (DTC)	475
9.1	Features	475
9.2	Register Descriptions	477
9.2.1	DTC Mode Register A (MRA)	477
9.2.2	DTC Mode Register B (MRB)	479
9.2.3	DTC Source Address Register (SAR)	480
9.2.4	DTC Destination Address Register (DAR)	480
9.2.5	DTC Transfer Count Register A (CRA)	480
9.2.6	DTC Transfer Count Register B (CRB)	480
9.2.7	DTC Enable Registers A to I (DTCERA to DTCERI)	481
9.2.8	DTC Vector Register (DTVECR)	481
9.2.9	DTC Control Register (DTCCR)	482
9.3	Activation Sources	483

9.4	Location of Register Information and DTC Vector Table	485
9.5	Operation	489
9.5.1	Normal Mode.....	492
9.5.2	Repeat Mode.....	493
9.5.3	Block Transfer Mode	494
9.5.4	Chain Transfer	495
9.5.5	Interrupt Sources.....	496
9.5.6	Operation Timing.....	496
9.5.7	Number of DTC Execution States	498
9.6	Procedures for Using DTC.....	500
9.6.1	Activation by Interrupt.....	500
9.6.2	Activation by Software	500
9.7	Examples of Use of the DTC.....	501
9.7.1	Normal Mode.....	501
9.7.2	Chain Transfer	502
9.7.3	Chain Transfer when Counter = 0.....	503
9.7.4	Software Activation	505
9.8	Usage Notes	506
9.8.1	Module Stop Function Setting	506
9.8.2	On-Chip RAM	506
9.8.3	DTCE Bit Setting.....	506
9.8.4	DMAC Transfer End Interrupt.....	506
9.8.5	Chain Transfer	506
Section 10	I/O Ports.....	507
10.1	Port 1.....	521
10.1.1	Port 1 Data Direction Register (P1DDR).....	521
10.1.2	Port 1 Data Register (P1DR).....	522
10.1.3	Port 1 Register (PORT1).....	522
10.1.4	Port 1 Open Drain Control Register (P1ODR)	523
10.1.5	Pin Functions	524
10.2	Port 2.....	547
10.2.1	Port 2 Data Direction Register (P2DDR).....	547
10.2.2	Port 2 Data Register (P2DR).....	548
10.2.3	Port 2 Register (PORT2).....	548
10.2.4	Port 2 Open Drain Control Register (P2ODR)	549
10.2.5	Pin Functions	550
10.3	Port 3.....	569
10.3.1	Port 3 Data Direction Register (P3DDR).....	569
10.3.2	Port 3 Data Register (P3DR).....	570

10.3.3	Port 3 Register (PORT3).....	570
10.3.4	Port 3 Open Drain Control Register (P3ODR)	571
10.3.5	Pin Functions	572
10.4	Port 4.....	575
10.4.1	Port 4 Register (PORT4).....	575
10.4.2	Pin Functions	575
10.5	Port 5.....	577
10.5.1	Port 5 Data Direction Register (P5DDR).....	577
10.5.2	Port 5 Data Register (P5DR).....	577
10.5.3	Port 5 Register (PORT5).....	578
10.5.4	Port 5 Open Drain Control Register (P5ODR)	578
10.5.5	Pin Functions	579
10.6	Port 6.....	586
10.6.1	Port 6 Data Direction Register (P6DDR).....	586
10.6.2	Port 6 Data Register (P6DR).....	587
10.6.3	Port 6 Register (PORT6).....	587
10.6.4	Port 6 Open Drain Control Register (P6ODR)	588
10.6.5	Pin Functions	588
10.7	Port 8.....	592
10.7.1	Port 8 Data Direction Register (P8DDR).....	592
10.7.2	Port 8 Data Register (P8DR).....	593
10.7.3	Port 8 Register (PORT8).....	593
10.7.4	Port 8 Open Drain Control Register (P8ODR)	594
10.7.5	Pin Functions	595
10.8	Port 9.....	605
10.8.1	Port 9 Register (PORT9).....	605
10.8.2	Pin Functions	606
10.9	Port A.....	608
10.9.1	Port A Data Direction Register (PADDDR).....	609
10.9.2	Port A Data Register (PADR).....	611
10.9.3	Port A Register (PORTA).....	611
10.9.4	Port A Pull-Up MOS Control Register (PAPCR)	612
10.9.5	Port A Open Drain Control Register (PAODR).....	612
10.9.6	Pin Functions	613
10.9.7	Port A Input Pull-Up MOS States.....	622
10.10	Port B.....	623
10.10.1	Port B Data Direction Register (PBDDR)	623
10.10.2	Port B Data Register (PBDR)	624
10.10.3	Port B Register (PORTB)	624
10.10.4	Port B Pull-Up MOS Control Register (PBPCR)	625

10.10.5 Port B Open Drain Control Register (PBODR)	625
10.10.6 Pin Functions	626
10.10.7 Port B Input Pull-Up MOS States	634
10.11 Port C	635
10.11.1 Port C Data Direction Register (PCDDR)	635
10.11.2 Port C Data Register (PCDR)	636
10.11.3 Port C Register (PORTC)	636
10.11.4 Port C Pull-Up MOS Control Register (PCPCR)	637
10.11.5 Port C Open Drain Control Register (PCODR)	637
10.11.6 Pin Functions	638
10.11.7 Port C Input Pull-Up MOS States	646
10.12 Port D	647
10.12.1 Port D Data Direction Register (PDDDR)	647
10.12.2 Port D Data Register (PDDR)	648
10.12.3 Port D Register (PORTD)	648
10.12.4 Port D Pull-Up MOS Control Register (PDPCR)	649
10.12.5 Port D Open Drain Control Register (PDODR)	649
10.12.6 Pin Functions	650
10.12.7 Port D Input Pull-Up MOS States	651
10.13 Port E	652
10.13.1 Port E Data Direction Register (PEDDR)	652
10.13.2 Port E Data Register (PEDR)	653
10.13.3 Port E Register (PORTE)	653
10.13.4 Port E Pull-Up MOS Control Register (PEPCR)	654
10.13.5 Port E Open Drain Control Register (PEODR)	654
10.13.6 Pin Functions	655
10.13.7 Port E Input Pull-Up MOS States	656
10.14 Port F	657
10.14.1 Port F Data Direction Register (PFDDR)	658
10.14.2 Port F Data Register (PFDR)	660
10.14.3 Port F Register (PORTF)	660
10.14.4 Port F Open Drain Control Register (PFODR)	661
10.14.5 Pin Functions	661
10.15 Port G	674
10.15.1 Port G Data Direction Register (PGDDR)	675
10.15.2 Port G Data Register (PGDR)	676
10.15.3 Port G Register (PORTG)	676
10.15.4 Port G Open Drain Control Register (PGODR)	677
10.15.5 Pin Functions	678
10.16 Port H	682

10.16.1 Port H Data Direction Register (PHDDR).....	682
10.16.2 Port H Data Register (PHDR).....	684
10.16.3 Port H Register (PORTH).....	684
10.16.4 Port H Open Drain Control Register (PHODR).....	685
10.16.5 Pin Functions	686
10.17 Port J	690
10.17.1 Port J Data Direction Register (PJDDR).....	690
10.17.2 Port J Data Register (PJDR)	690
10.17.3 Port J Register (PORTJ)	691
10.17.4 Port J Open Drain Control Register (PJODR)	691
10.17.5 Pin Functions	692
10.18 Port Function Control Registers.....	693
10.18.1 Port Function Control Register 0 (PFCR0).....	693
10.18.2 Port Function Control Register 1 (PFCR1).....	694
10.18.3 Port Function Control Register 2 (PFCR2).....	696
10.18.4 Port Function Control Register 3 (PFCR3).....	697
10.18.5 Port Function Control Register 4 (PFCR4).....	698
10.18.6 Port Function Control Register 5 (PFCR5).....	700
 Section 11 16-Bit Timer Pulse Unit (TPU)	 701
11.1 Features.....	701
11.2 Input/Output Pins	708
11.3 Register Descriptions	711
11.3.1 Timer Control Register (TCR).....	716
11.3.2 Timer Mode Register (TMDR).....	721
11.3.3 Timer I/O Control Register (TIOR).....	723
11.3.4 Timer Interrupt Enable Register (TIER).....	740
11.3.5 Timer Status Register (TSR).....	742
11.3.6 Timer Counter (TCNT).....	745
11.3.7 Timer General Register (TGR)	745
11.3.8 Timer Start Register (TSTR)	745
11.3.9 Timer Synchronous Register (TSYR).....	746
11.3.10 Timer Start Register B (TSTRB)	747
11.3.11 Timer Synchronous Register B (TSYRB)	748
11.4 Operation	749
11.4.1 Basic Functions.....	749
11.4.2 Synchronous Operation.....	756
11.4.3 Buffer Operation	759
11.4.4 Cascaded Operation	763
11.4.5 PWM Modes	765

11.4.6	Phase Counting Mode.....	771
11.5	Interrupt Sources.....	779
11.6	DTC Activation.....	783
11.7	DMAC Activation.....	783
11.8	A/D Converter Activation.....	783
11.9	Operation Timing.....	784
11.9.1	Input/Output Timing.....	784
11.9.2	Interrupt Signal Timing	789
11.10	Usage Notes	793
11.10.1	Module Stop Function Setting	793
11.10.2	Input Clock Restrictions	793
11.10.3	Caution on Cycle Setting	794
11.10.4	Contention between TCNT Write and Clear Operations	794
11.10.5	Contention between TCNT Write and Increment Operations.....	795
11.10.6	Contention between TGR Write and Compare Match	796
11.10.7	Contention between Buffer Register Write and Compare Match	797
11.10.8	Contention between TGR Read and Input Capture.....	798
11.10.9	Contention between TGR Write and Input Capture.....	799
11.10.10	Contention between Buffer Register Write and Input Capture	800
11.10.11	Contention between Overflow/Underflow and Counter Clearing	801
11.10.12	Contention between TCNT Write and Overflow/Underflow	802
11.10.13	Multiplexing of I/O Pins	802
11.10.14	Interrupts and Module Stop Mode	802
Section 12	Programmable Pulse Generator (PPG)	803
12.1	Features.....	803
12.2	Input/Output Pins	805
12.3	Register Descriptions	806
12.3.1	Next Data Enable Registers H, L (NDERH, NDERL)	807
12.3.2	Output Data Registers H, L (PODRH, PODRL).....	808
12.3.3	Next Data Registers H, L (NDRH, NDRL)	809
12.3.4	PPG Output Control Register (PCR)	812
12.3.5	PPG Output Mode Register (PMR)	813
12.4	Operation	815
12.4.1	Output Timing	816
12.4.2	Sample Setup Procedure for Normal Pulse Output.....	817
12.4.3	Example of Normal Pulse Output (Example of Five-Phase Pulse Output).....	818
12.4.4	Non-Overlapping Pulse Output.....	819
12.4.5	Sample Setup Procedure for Non-Overlapping Pulse Output.....	821

12.4.6	Example of Non-Overlapping Pulse Output (Example of Four-Phase Complementary Non-Overlapping Output)	822
12.4.7	Inverted Pulse Output	824
12.4.8	Pulse Output Triggered by Input Capture	825
12.5	Usage Notes	826
12.5.1	Module Stop Function Setting	826
12.5.2	Operation of Pulse Output Pins.....	826
Section 13	8-Bit Timers (TMR).....	827
13.1	Features.....	827
13.2	Input/Output Pins	829
13.3	Register Descriptions	829
13.3.1	Timer Counter (TCNT).....	830
13.3.2	Time Constant Register A (TCORA).....	830
13.3.3	Time Constant Register B (TCORB)	830
13.3.4	Timer Control Register (TCR).....	831
13.3.5	Timer Counter Control Register (TCCR)	832
13.3.6	Timer Control/Status Register (TCSR).....	834
13.4	Operation	838
13.4.1	Pulse Output.....	838
13.4.2	Reset Input	839
13.5	Operation Timing	840
13.5.1	TCNT Incrementation Timing	840
13.5.2	Timing of CMFA and CMFB Setting when Compare-Match Occurs	841
13.5.3	Timing of Timer Output when Compare-Match Occurs.....	842
13.5.4	Timing of Compare Match Clear	842
13.5.5	Timing of TCNT External Reset.....	843
13.5.6	Timing of Overflow Flag (OVF) Setting	843
13.6	Operation with Cascaded Connection.....	844
13.6.1	16-Bit Counter Mode	844
13.6.2	Compare Match Count Mode.....	844
13.7	Interrupt Sources.....	845
13.7.1	Interrupt Sources and DTC Activation	845
13.7.2	A/D Converter Activation.....	845
13.8	Usage Notes	846
13.8.1	Contention between TCNT Write and Clear.....	846
13.8.2	Contention between TCNT Write and Increment	847
13.8.3	Contention between TCOR Write and Compare Match	848
13.8.4	Contention between Compare Matches A and B	849
13.8.5	Switching of Internal Clocks and TCNT Operation	849

13.8.6	Mode Setting with Cascaded Connection	851
13.8.7	Module Stop Function Setting	851
13.8.8	Interrupts in Module Stop State	851
Section 14 Watchdog Timer (WDT)		853
14.1	Features.....	853
14.2	Input/Output Pin	854
14.3	Register Descriptions	855
14.3.1	Timer Counter (TCNT).....	855
14.3.2	Timer Control/Status Register (TCSR).....	855
14.3.3	Reset Control/Status Register (RSTCSR).....	857
14.4	Operation	858
14.4.1	Watchdog Timer Mode	858
14.4.2	Interval Timer Mode.....	860
14.5	Interrupt Source	860
14.6	Usage Notes	861
14.6.1	Notes on Register Access	861
14.6.2	Contention between Timer Counter (TCNT) Write and Increment.....	863
14.6.3	Changing Value of CKS2 to CKS0	863
14.6.4	Switching between Watchdog Timer Mode and Interval Timer Mode.....	863
14.6.5	Internal Reset in Watchdog Timer Mode.....	864
14.6.6	System Reset by <u>WDT</u> OVF Signal.....	864
Section 15 Serial Communication Interface (SCI, IrDA)		865
15.1	Features.....	865
15.2	Input/Output Pins	868
15.3	Register Descriptions	869
15.3.1	Receive Shift Register (RSR)	870
15.3.2	Receive Data Register (RDR).....	870
15.3.3	Transmit Data Register (TDR).....	871
15.3.4	Transmit Shift Register (TSR)	871
15.3.5	Serial Mode Register (SMR)	871
15.3.6	Serial Control Register (SCR)	875
15.3.7	Serial Status Register (SSR)	880
15.3.8	Smart Card Mode Register (SCMR).....	888
15.3.9	Bit Rate Register (BRR)	889
15.3.10	IrDA Control Register (IrCR).....	897
15.3.11	Serial Extension Mode Register (SEMR)	898
15.4	Operation in Asynchronous Mode	900
15.4.1	Data Transfer Format.....	900

15.4.2	Receive Data Sampling Timing and Reception Margin in Asynchronous Mode	902
15.4.3	Clock	903
15.4.4	SCI Initialization (Asynchronous Mode)	904
15.4.5	Data Transmission (Asynchronous Mode)	905
15.4.6	Serial Data Reception (Asynchronous Mode)	907
15.5	Multiprocessor Communication Function	911
15.5.1	Multiprocessor Serial Data Transmission	912
15.5.2	Multiprocessor Serial Data Reception	914
15.6	Operation in Clocked Synchronous Mode	918
15.6.1	Clock	918
15.6.2	SCI Initialization (Clocked Synchronous Mode)	919
15.6.3	Serial Data Transmission (Clocked Synchronous Mode)	920
15.6.4	Serial Data Reception (Clocked Synchronous Mode)	923
15.6.5	Simultaneous Serial Data Transmission and Reception (Clocked Synchronous Mode)	925
15.7	Operation in Smart Card Interface Mode	927
15.7.1	Pin Connection Example	927
15.7.2	Data Format (Except for Block Transfer Mode)	928
15.7.3	Block Transfer Mode	929
15.7.4	Receive Data Sampling Timing and Reception Margin	930
15.7.5	Initialization	932
15.7.6	Data Transmission (Except for Block Transfer Mode)	933
15.7.7	Serial Data Reception (Except for Block Transfer Mode)	936
15.7.8	Clock Output Control	938
15.8	IrDA Operation	940
15.9	Interrupt Sources	944
15.9.1	Interrupts in Normal Serial Communication Interface Mode	944
15.9.2	Interrupts in Smart Card Interface Mode	946
15.10	Usage Notes	948
15.10.1	Module Stop Function Setting	948
15.10.2	Break Detection and Processing	948
15.10.3	Mark State and Break Sending	948
15.10.4	Receive Error Flags and Transmit Operations (Clocked Synchronous Mode Only)	948
15.10.5	Relation between Writes to TDR and the TDRE Flag	949
15.10.6	Restrictions on Use of DMAC or DTC	949
15.10.7	Operation in Case of Mode Transition	950

Section 16	I ² C Bus Interface 2 (IIC2).....	955
16.1	Features.....	955
16.2	Input/Output Pins.....	957
16.3	Register Descriptions.....	958
16.3.1	I ² C Bus Control Register A (ICCRA).....	960
16.3.2	I ² C Bus Control Register B (ICCRB)	962
16.3.3	I ² C Bus Mode Register (ICMR).....	963
16.3.4	I ² C Bus Interrupt Enable Register (ICIER).....	965
16.3.5	I ² C Bus Status Register (ICSR).....	967
16.3.6	Slave Address Register (SAR).....	969
16.3.7	I ² C Bus Transmit Data Register (ICDRT)	970
16.3.8	I ² C Bus Receive Data Register (ICDRR).....	970
16.3.9	I ² C Bus Shift Register (ICDRS).....	970
16.4	Operation	971
16.4.1	I ² C Bus Format.....	971
16.4.2	Master Transmit Operation.....	972
16.4.3	Master Receive Operation	974
16.4.4	Slave Transmit Operation	976
16.4.5	Slave Receive Operation.....	979
16.4.6	Noise Canceler.....	981
16.4.7	Example of Use.....	981
16.5	Interrupt Request.....	986
16.6	Bit Synchronous Circuit.....	987
16.7	Usage Notes	988
Section 17	A/D Converter	991
17.1	Features.....	991
17.2	Input/Output Pins.....	994
17.3	Register Descriptions.....	996
17.3.1	A/D Data Registers A to H (ADDRA to ADDRH)	997
17.3.2	A/D Control/Status Register for Unit 0 (ADCSR_0).....	999
17.3.3	A/D Control/Status Register for Unit 1 (ADCSR_1).....	1001
17.3.4	A/D Control Register (ADCR_0) Unit 0	1004
17.3.5	A/D Control Register (ADCR_1) Unit 1	1006
17.4	Operation	1008
17.4.1	Single Mode.....	1008
17.4.2	Scan Mode	1010
17.4.3	Input Sampling and A/D Conversion Time	1014
17.4.4	External Trigger Input Timing.....	1016

17.5	Interrupt Source	1017
17.6	A/D Conversion Accuracy Definitions	1018
17.7	Usage Notes	1020
17.7.1	Module Stop Function Setting	1020
17.7.2	A/D Input Hold Function in Software Standby Mode	1020
17.7.3	Restarting the A/D Converter	1020
17.7.4	Permissible Signal Source Impedance	1021
17.7.5	Influences on Absolute Accuracy	1022
17.7.6	Setting Range of Analog Power Supply and Other Pins	1022
17.7.7	Notes on Board Design	1023
17.7.8	Notes on Noise Countermeasures	1023
17.7.9	Concurrent Operation of Two A/D Converters.....	1025
17.7.10	Notes on Start of A/D Conversion by Conversion Start Trigger from TPU (Units 0 and 1)	1026
Section 18 D/A Converter.....		1027
18.1	Features.....	1027
18.2	Input/Output Pins	1029
18.3	Register Descriptions	1030
18.3.1	D/A Data Registers 2 and 3 (DADR2 and DADR3).....	1030
18.3.2	D/A Control Register 23 (DACR23)	1030
18.4	Operation	1033
18.5	Usage Notes	1035
18.5.1	Module Stop Function Setting	1035
18.5.2	D/A Output Hold Function in Software Standby Mode.....	1035
Section 19 Synchronous Serial Communication Unit (SSU)		1037
19.1	Features.....	1037
19.2	Input/Output Pins	1039
19.3	Register Descriptions	1039
19.3.1	SS Control Register H (SSCRH)	1040
19.3.2	SS Control Register L (SSCRL)	1042
19.3.3	SS Mode Register (SSMR)	1043
19.3.4	SS Enable Register (SSER)	1044
19.3.5	SS Status Register (SSSR)	1045
19.3.6	SS Control Register 2 (SSCR2)	1047
19.3.7	SS Transmit Data Registers 0 to 3 (SSTDR0 to SSTDR3).....	1049
19.3.8	SS Receive Data Registers 0 to 3 (SSRDR0 to SSRDR3).....	1050
19.3.9	SS Shift Register (SSTRSR).....	1050
19.4	Operation	1051